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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor: Mika KIRITANI)

Serial No.: 09/887,104)

Filed: June 25, 2001)

For: SEMICONDUCTOR RESIN MOLD)
AND SEMICONDUCTOR RESIN)
MOLDING METHOD USING THE)
MOLD)

Assistant Commissioner for Patents
Washington, DC 20231

) Group Art Unit: 1722

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Sir:

CLAIM FOR PRIORITY

Under the provisions of Section 119 of 35 U.S.C., applicant hereby claims the benefit of Japanese Patent Application No. 2001-188772, filed June 21, 2001, for the above identified United States Patent Application.

Respectfully submitted,
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